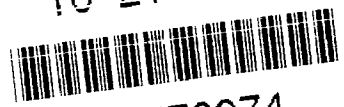


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U.S. DEPARTMENT OF COMMERCE
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102578974

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): **10-7-03**
Yian-Liang Kuo
Yu-Chang Lin
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
Name: Taiwan Semiconductor Manufacturing Co., Ltd.
Internal Address: _____
Street Address: No. 8, Li-Hsin Road 6
Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77
City: Hsin-Chu State: _____ Zip: 300-77
Additional name(s) & address(es) attached? Yes No

22141 U.S. PTO
10/680664



3. Nature of conveyance:
 Assignment Merger
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 Other _____
Execution Date: September 6, 2003

4. Application number(s) or patent number(s): **10680664**
If this document is being filed together with a new application, the execution date of the application is: _____
A. Patent Application No.(s) _____
B. Patent No.(s) _____
Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: David M. O'Dell
Internal Address: _____
Street Address: Haynes and Boone, LLP
901 Main Street, Suite 3100
City: Dallas State: TX Zip: 75202

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41).....\$ 40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number:
08-1394

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9. Signature.
10/21/2003 **LMUELLER 00000092 081394 10680664**
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Timothy Bliss
Name of Person Signing

Timothy Bliss
Signature

10/21/03
Date

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:
Mail Stop Assignment, Commissioner of Patent, P.O. Box 1450
Alexandria, VA 22313-1450

Patent / Docket No.: 24061.43/TSMC2002-0978

Customer No. 27683

ASSIGNMENT

WHEREAS, we

(1) Yian-Liang Kuo of

(2) Yu-Chang Lin of

have invented certain improvements in

**INTEGRATED CIRCUIT PACKAGE BOND PAD
HAVING PLURALITY OF CONDUCTIVE MEMBERS**

for which we have executed an application for Letters Patent of the United States of America, of even date herewith; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Inc., ("TSMC"), No. 6, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths

PATENT / DOCKET NO.: 24061.43/TSMC2002-0978
CUSTOMER NO. 27683

FULL NAME OF INVENTOR: Yian-Liang Kuo

INVENTOR'S SIGNATURE: Yian-Liang Kuo

DATED: 9/2, 2003

RESIDENCE: Str., No.3, Alley 1, Lane 51, Shiping Rd., HsinChu City.

POST OFFICE ADDRESS:

No.9, Ozation Rd. 1, Science-based industrial park, Hsin-Chu, Taiwan 300-77, P.O.C

FULL NAME OF INVENTOR: Yu-Chang Lin

INVENTOR'S SIGNATURE: [Signature]

DATED: 9/6 2003

RESIDENCE: No. 2-3, Alley 7, Lane 76, Guanghua E. St., Hsinchu City 300, Taiwan

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R53874

TOTAL P.05